

# 18<sup>th</sup> European Wet & 47<sup>th</sup> European CMP Users Meeting

Wet-Session: Thursday, April 18, 2024, 13:30 – 18:15

CMP-Session: Friday, April 19, 2024, 09:15 – 12:55

Hotel Warmbaderhof, Warmbad-Villach, Austria

Organized by European CMP&WET Usergroup

## Agenda Thursday, April 18<sup>th</sup>

- 12:30 Welcome Coffee, Tea, Softdrinks and Light Lunch
- 13:30 Opening Remarks & Welcome  
Knut Gottfried  
Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany
- Wet Processes: Session 1**  
Session Chair: Knut Gottfried, Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany
- 13:35 Integrated Metrology in Wet Chemical Semiconductor Equipment  
Martin Huber  
NexGen Wafer Systems GmbH, Villach, Austria
- 14:00 Next Generation of Automation in Wet Processing  
Patrick Hirt  
AP&S International GmbH, Donaueschingen, Germany
- 14:25 Flucto-Clean® – A Novel Method for Post-CMP Cleaning  
Ara Philipossian  
SPS, Araca, United States
- 14:50 Innovative Wet Chemical Cleaning Equipment from South Korea  
John Oshinowo  
John Oshinowo Consulting, Hamburg, Germany
- 15:05 Transferring from Dry Metal+Barrier Etching to Wet Etching on 300mm  
Moritz Mittermayr  
Siconnex GmbH, Hof bei Salzburg, Austria
- 15:30 Coffee Break**
- Wet Processes: Session 2**  
Session Chair: Gerfried Zwicker, zwickerconsult, Berlin, Germany
- 16:00 Adapting Selectivity of Thermal Silicon Oxide to Deposited Silicon Oxide in Wet Etching Process  
Hans Kruwinus  
PTW SpinTec, Villach, Austria
- 16:25 True circular economy for your solvents through on spot distillation  
Andreas Dietrich  
Fäth GmbH, Munich, Germany
- 16:45 Is Reclaimed Water the Better UPW Source? - Synergies of Water Reclaim for Primary Water Recycling Concepts –  
Jochen Ruth  
Pall GmbH, Dreieich, Germany
- 17:10 European Partnerships for Developing Wet Processes  
Harold Le Tulzo  
Technic, La plaine St Denis, France

- 17:35 *Hybrid Presentation: Packaging Suitable for the Cleanroom*  
Emanuel Rothmayr  
Comprei Reinraum- Handel- und Schulungs GmbH, Villach, Austria
- 17:50 *Online Presentation: Using Aerosol Metrology to Deliver Discrete, Nanometer-Scale Particle Size Measurement for CMP Slurry*  
Andrea Tiwari, Daniel Troolin  
TSI, Shoreview, MN, USA
- 18:10 *Enhanced Efficiency in Positive Photoresist Stripping: The Role of UV Flood Exposure*  
Naveen Reddy  
imec, Leuven, Belgium
- 18:15 End of Wet Users Meeting / time for networking and discussion
- 19:00 Workshop Dinner at Hotel Warmbaderhof  
Dinner Speech: "Wirtschaftsstandort Kärnten"  
Thereza Christina Grollitsch  
BABEG Kärntner Betriebsansiedlungs- und Beteiligungsgesellschaft mbH, Klagenfurt, Austria

### **Agenda Friday, April 19<sup>th</sup>**

- 8:45 Good Morning Coffee, Tea, Softdrinks
- 9:15 Opening Remarks  
Gerfried Zwicker  
zwickerconsult, Berlin, Germany
- 9:20 **Tutorial:** Dielectric CMP  
Federico Barbieri  
Entegris/CMC Materials, Barry / Vale of Glamorgan, United Kingdom
- CMP Processes: Session 1**  
Session Chair: Martin Kulawski, Advaplan, Espoo, Finland
- 10:10 SensArray Wireless In-Situ CMP-Temp Measurement - Correlation Between Film Removal and Wafer Temperature  
Bernard Winker  
KLA-Tencor GmbH, Dresden, Germany
- 10:25 Challenges for Thick Layer Oxide CMP  
Bart Kenens  
imec, Leuven, Belgium
- 10:40 Reducing Variations in Process Chamber Pressure by Actively Controlling Exhaust  
Gabriel Park  
Levitronix GmbH, Zurich, Switzerland
- 10:55 Coffee Break**
- CMP Processes: Session 2**  
Session Chair: Benjamin Steible, Fraunhofer ISIT, Itzehoe, Germany
- 11:25 Lowering the Cost of Ceria-Based STI CMP Processes  
Ara Philipossian  
Araca, Tucson, AZ, United States
- 11:50 A Novel Cleanliness Assessment Method for CMP Slurries  
Jochen Ruth  
Pall GmbH, Dreieich, Germany

- 12:15 Hybrid Bonding CMP: Metrology & Defectivity Challenges  
Steven Deckers  
imec, Leuven, Belgium
- 12:30 Further uniformity improvement of SiC wafers after CMP  
Thoralf Dunger  
Scia Systems GmbH
- 12:50 Polishing Solutions for High Rate Silicon CMP  
Glenn Whitener  
Fujimi Corporation
- 13:15 End of CMP Users Meeting / time for networking and discussion  
Coffee, Tea, Softdrinks, Snacks and Light Lunch



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